

An IATF 16949, ISO9001 and ISO 14001 Certified Company





0.8 Amp BRIDGE RECTIFIERSSingle Phase . GLASS PASSIVATED







MBS package RoHS compliant

FEATURES:

- 1. The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- 2.Idea for printed circuit board
- 3. Glass passivated Junction chip
- 4.Low reverse leakage
- 5. High forward surge current capability
- 6. High temperature soldering guaranteed 250°C/10 seconds at terminals

Maximum Ratings And Electrical Characteristics

Ratings at 25 C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load for capacitive load current derate by 20%.

PARAMETE	SYMBOL	MB2S	MB4S	MB6S	MB8S	MB10S	UNITS	
Maximum repetitive peak re	V_{RRM}	200	400	600	800	1000	VOLTS	
Maximum RMS voltage		V_{RMS}	140	280	420	560	700	VOLTS
Maximum DC blocking volta	ige	V_{DC}	200	400	600	800	1000	VOLTS
Maximum average forward TL=100° C On glass-epoxy	I _(AV)	0.8				Amp		
Peak forward surge current sine-wave superimposed or	I _{FSM}	30.0				Amp		
Rating for fusing (t=8.3ms,	l ² t	3.74				Amp		
Maximum instantaneous for 0.4A	V _F	1.10				VOLTS		
Maximum DC reverse T _A =25 C			5.0					
current at rated DC blocking voltage	T _A =125 C	I _R	500				μΑ	
Typical junction capacitance	CJ	15.0			pF			
Typical thermal resistance	$R_{\theta JA}$	85.0			°C/W			
Operating junction and stora	T_J , T_{STG}	-55 to +155			°C			

Notes:

- 1. Mounted on glass epoxy PC board with 1.3*1.3mm solder pad
- 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

MB2S-MB10S Rev0 12042019 ESW







An IATF 16949, ISO9001 and ISO 14001 Certified Company

Typical Characteristic curves

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

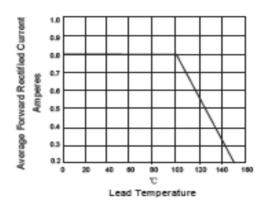


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

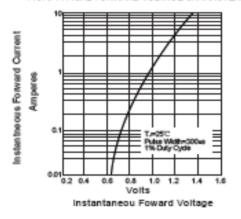


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PERLEG

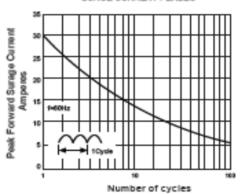
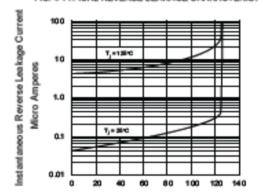


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS



Percent Of Rated Peak Reverse Voltage(%)



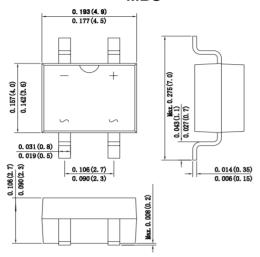




An IATF 16949, ISO9001 and ISO 14001 Certified Company

Package Details

MBS



Mechanical Data

Case: Molded plastic body

Terminals: Solder plated, solderable per MIL-STD-750,

Method 2026

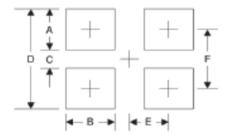
Polarity: Polarity symbol marking on body

Mounting Position: Any

Weight: 0.004 ounce, 0.118 grams

Dimensions in inches and (millimeters)

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
Α	1.7	0.067
В	1.0	0.039
С	4.40	0.173
D	8.10	0.319
E	1.25	0.049
F	6.30	0.248

Note: For AECQ compliant products, please suffix -AH in the part number while ordering

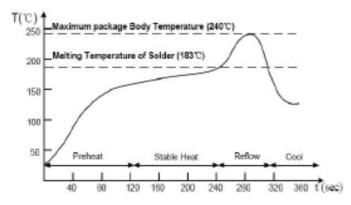






An IATF 16949, ISO9001 and ISO 14001 Certified Company

Suggested Soldering Temperature Profile

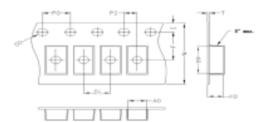


Note

- → The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- → Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Carrier Dimension(mm)



A0	В0	ко	D0	E	F
5.10	7.20	2.88	1.55	1.75	5.50
PO	Pl	P2	T	w	Tolerance
4.0	8.0	2.0	0.25	12	0.1

Package Specifications

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
MBS	13'	330	3	338	6	365*365*360	48







An IATF 16949, ISO9001 and ISO 14001 Certified Company

Recommended Product Storage Environment for Diode and Transistors

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- Temperature 5 °C to 30 °C
- Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- Avoid outdoor exposure or storage in areas subject to rain or water spraying.
- Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- Avoid condensation.
- Mechanical stress such as vibration and impact shall be avoided.
- The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years, the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start. For this the following JEDEC table may be referred:

JEDEC MSL Level						
Level	Time	Condition				
1	Unlimited	≤30 °C / 85% RH				
2	1 Year	≤30 °C / 60% RH				
2a	4 Weeks	≤30 °C / 60% RH				
3	168 Hours	≤30 °C / 60% RH				
4	72 Hours	≤30 °C / 60% RH				
5	48 Hours	≤30 °C / 60% RH				
5a	24 Hours	≤30 °C / 60% RH				
6	Time on Label(TOL)	≤30 °C / 60% RH				

Figure 1 Floor Life according to JEDEC MSL Level

MB2S-MB10S Rev0 12042019 ESW







Customer Notes

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



CDIL is a registered Trademark of Continental Device India Pvt.Limited

C-120 Naraina Industrial Area, New Delhi 110 028, India.
Telephone + 91-11-2579 6150, 4141 1112 Fax + 91-11-2579 5290, 4141 1119

CIN No. - U32109DL1964PTC004291

MB2S-MB10S Rev0 12042019 ESW